

**Amendments to the Specification:**

Please replace the paragraph starting at page 4, line 3 with the following amended paragraph:

-- The invention provides a dispense head for a semiconductor substrate, or wafer, processing apparatus. The dispense head may include an inlet, at least one outlet, a drain, and a passageway therethrough interconnecting the inlet, the outlet, and the drain. The inlet may be at a first height above a bottom of the passageway, the outlet may be at a second height above the bottom, and the drain may be at a third height above the bottom. A first valve may be connected to the inlet, and a second valve may be connected to the drain. When the first valve is opened and the second valve is closed, fluid flows into the inlet and out of the outlet. When the second valve is opened and the first valve is closed, fluid from the passageway flows out of the drain. A pump may be connected to the drain.

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Please replace paragraph [0010] with the following amended paragraph:

[0010] Figure 1 to Figure 4f of the accompanying drawings illustrate a dispense head for a semiconductor substrate, or wafer, processing apparatus. The dispense head may include an inlet, at least one outlet, a drain, and a passageway therethrough interconnecting the inlet, the outlet, and the drain. The inlet may be at a first height above a bottom of the passageway, the outlet may be at a second height above the bottom, and the drain may be at a third height above the bottom. A first valve may be connected to the inlet, and a second valve may be connected to the drain. When the first valve is opened and the second valve is closed, fluid flows into the inlet and out of the outlet. When the second valve is opened and the first valve is closed, fluid from the passageway flows out of the drain. A pump may be connected to the drain.

Please replace the Abstract with the amended Abstract on the following page.